



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-07-07
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	TSFP*ED6EB6F	A	Z8GA	2015-07-07
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2X9.2X4.5	3	Through-hole	
Comment	Package: TO 220 ISO FULL PACK IN LINE; MDF valid for STP55NF06FP			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TSFP*ED6EBGF					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	6.025	mg	supplier	die	Silicon (Si)	7440-21-3		5.83	mg	967635	3068
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.113	mg	18755	59
Die or Dies				supplier	Passivation	Silicon Oxide	7631-86-9		0.031	mg	5145	16
Die or Dies				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	498	2
Die or Dies				supplier	back side metallization	Gold (Au)	7440-57-5		0.008	mg	1328	4
Die or Dies				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.04	mg	6639	21
Leadframe	Copper & its alloys	580.099	mg	supplier	alloy	Copper (Cu)	7440-50-8		576.526	mg	993841	303435
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.578	mg	996	304
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.173	mg	298	91
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		2.805	mg	4835	1476
Leadframe				supplier	metallization	Phosphorus (P)	12185-10-3		0.017	mg	29	9
Soft solder	Solder	5.018	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.793	mg	955161	2523
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.125	mg	24910	66
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.1	mg	19928	53
Bonding wire	Other inorganic materials	1.047	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.047	mg	1000000	551
encapsulation	Other inorganic materials	1301.943	mg	supplier	mold compound	Silica, vitreous	60676-86-0		97.646	mg	75000	51393
encapsulation				supplier	mold compound	Quartz	14808-60-7		911.359	mg	699999	479663
encapsulation				supplier	mold compound	Epoxy resin	25068-38-6		182.271	mg	139999	95932
encapsulation				supplier	mold compound	phenol resin	29690-82-2		91.137	mg	70001	47967
encapsulation				supplier	mold compound	carbon black	1333-86-4		6.51	mg	5000	3426
encapsulation				supplier	mold compound	metal hydroxide	Proprietary		13.02	mg	10000	6853
connections coating	Solder	5.868	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.868	mg	1000000	3088